Holtite® Series *Zero Profile Solderless DIP Sockets on Reel*

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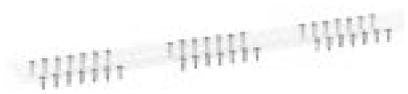


322-HCS5P2-314

FEATURES:

The solderless zero-profile Holtite® contact is designed to be press-fit into the plated-thru hole of a printed wiring board. This unique design allows the plated-thru hole to become the component socket. The outer conical shape of the Holtite® contact sizes the plated-thru hole when pressed into place. The precision-machined geometry allows for the controlled displacement of plated material without damaging the hole, or affecting the normal mechanical and electrical contact performance.

- Lowest socket profile
  The profile of the printed wiring board with the Holtite® contact installed is less than the length of the IC or component lead, offering the lowest socketing profile, permitting card rack spacing as low as .400", identical to that of direct soldering.
- Precision-machined, tapered-entry, four finger contact
  The underlying contact design used in the Holtite® system has a proven record of reliability after more than fifteen years' usage in both commercial and military applications.
- Retains minimum component lead lengths
  The socketing technique provides the shortest distance between the component seating plane and the contact engagement zone for maximum retention of short component leads.
- Maximum heat dissipation
  Open contact design permits air flow through the board, increasing heat dissipation and extending component life.
- Solderless, gas-tight, press-fit insertion
  The solderless, pluggable system saves the time and cost of soldering, plus eliminating the potential for heat damage, warpage and corrosive residue contamination..
- Removes artwork design restrictions
  Use of the Holtite® solderless system removes certain artwork restrictions necessary for wave soldering and solder joint construction. Line spacing can be made as tight as electrical parameters allow without solder bridging or the need for soldermask. Terminal areas can be reduced in diameter without the need of a base for solder fillets. Ground plane areas can be increased without concern for heat-induced warpage.
- Immediate conversion to the Holtite® system
  Existing printed wiring designs can be converted by simply changing the drilled hole diameter prior to plating.

MATERIAL SPECIFICATIONS:

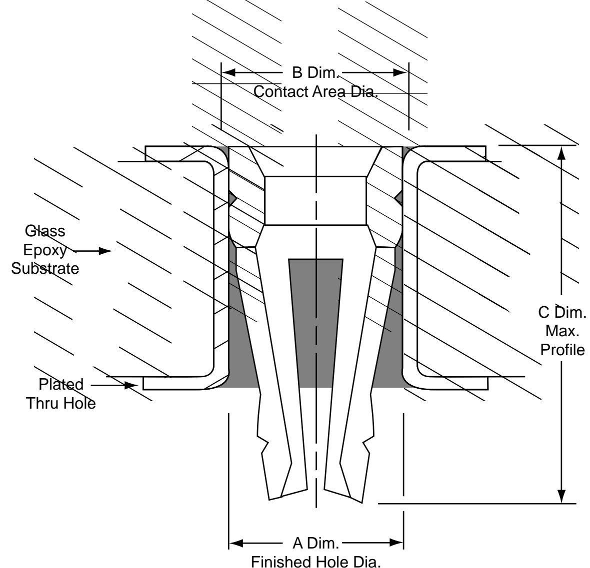
Carrier Strip .... Mylar
Contact .... Beryllium copper
Finish .... Gold or tin/lead plated

PERFORMANCE SPECIFICATIONS:

MECHANICAL
Vibration .... Passed MIL-STD-202, Method 204, 20 G's
Durability .... Passed MIL-STD-1344, Method 2016, 50 cycles
Insertion Force .... 92 Grams (3.2 oz.) average with a .018" (0,46) pol. steel pin and .043" (1,09) plated thru hole
Withdrawal Force .... 103 Grams (3.6 oz.) average with a .018" (0,46) pol. steel pin and .043" (1,09) plated thru hole
Contact Retention in Board .... 5 Lb. minimum

ELECTRICAL
Contact Resistance .... 10 Milliohms max.
Contact Rating .... 3 Amps

ENVIRONMENTAL
Humidity .... Passed MIL-STD-202, Method 106
Thermal Shock .... Passed MIL-STD-202, Method 107, Cond. F
Operation Temp. .... Gold contact -55°C to +125°C, Tin/lead contact -55°C to +105°C



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